

**Amendments to the Claims:**

Following is a complete listing of the claims pending in the application, as amended:

1-7. (Cancelled)

8. (Currently Amended) An apparatus for processing workpieces, comprising:

a semiconductor process machine having a deck~~device support having a first alignment surface;~~

a processing vessel in the semiconductor process machine~~carried by the device support at a carrying plane~~, the processing vessel being configured to receive at least one processing liquid;

a workpiece support ~~positioned~~ having a base attached to the deck of the semiconductor process machine and a moveable workpiece holder configured to carry the~~a~~ workpiece at least proximate to the processing vessel;

a drive unit operatively coupled to the workpiece support ~~holder to move~~ rotate the workpiece about an axis normal to the workpiece support relative to the ~~processing vessel;~~ and

~~a mounting portion coupled to the workpiece support and having a second alignment surface removably mated with the first alignment surface, with wherein the base of the workpiece support being supported relative to the device support only is at or above the deck~~ carrying plane.

9. (Currently Amended) The apparatus of claim 48 wherein the workpiece support is configured to also move the workpiece vertically between a processing position and a receive wafer position~~mounting portion includes a base.~~

10. (Currently Amended) The apparatus of claim 48 wherein the drive unit is operatively coupled to the workpiece support to rotate the workpiece support about a rotation axis.

11. (Currently Amended) The tool of claim 48 wherein the processing vessel is configured to receive an electrochemical processing liquid.

12. (Currently Amended) The apparatus of claim 48 wherein the processing vessel extends below the deck~~carrying plane~~.

13. (Currently Amended) The apparatus of claim 48 wherein the workpiece support is configured to carry the workpiece in contact with a processing liquid.

14. (Currently Amended) The apparatus of claim 48 wherein the workpiece support includes at least one contact assembly having at least one electrical contact positioned to make contact with the workpiece.

15. (Currently Amended) The apparatus of claim 48 wherein the workpiece support includes at least one electrode and at least one sheath positioned to seal against a surface of the workpiece.

16. (Currently Amended) The apparatus of claim 48 wherein the deck~~carrying plane~~ includes an aperture in which the processing vessel is received.